PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3450979

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
OSAMU KAKUTANI	06/16/2015
TAKATOSHI KAWAMURA	06/18/2015
KOHEI SEYAMA	06/18/2015
AKIRA SATO	06/18/2015

RECEIVING PARTY DATA

Name:	SHINKAWA LTD.
Street Address:	2-51-1 INADAIRA, MUSASHIMURAYAMA-SHI,
City:	TOKYO
State/Country:	JAPAN
Postal Code:	208-8585

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14731431

CORRESPONDENCE DATA

Fax Number: (510)580-7280

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: usa@jcipgroup.com.tw
Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE
Address Line 1: 7F.-1, NO. 100, ROOSEVELT RD., SEC. 2,
Address Line 4: TAIPEI, TAIWAN 100

ATTORNEY DOCKET NUMBER:	53845-US-1134-PCT(CA)
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	07/23/2015

Total Attachments: 2
source=53845-ASSIGN#page1.tif
source=53845-ASSIGN#page2.tif

ASSIGNMENT

WHEREAS,

1. OSAMU KAKUTANI
2. TAKATOSHI KAWAMURA
3. KOHEI SEYAMA
4. AKIRA SATO

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **BONDING TOOL COOLING APPARATUS AND METHOD FOR COOLING BONDING TOOL**

[x] Filed: June 05, 2015 Serial No. 14/731,431

[ ] Executed concurrently with the execution of this instrument

WHEREAS, **SHINKAWA LTD.**
of 2-51-1 INADAIRA, MUSASHIMURAYAMA-SHI, TOKYO 208-8585 JAPAN

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Osamu Kakutani Date: June, 16, 2015
Sole or First Joint Inventor: OSAMU KAKUTANI

Signature: Takatoshi Kawamura Date: June, 18, 2015
Second Joint Inventor: TAKATOSHI KAWAMURA

Signature: Kohei Seyama Date: June, 18, 2015
Third Joint Inventor: KOHEI SEYAMA

Signature: Akira Sato Date: June, 18, 2015
Fourth Joint Inventor: AKIRA SATO